

High Efficiency Thyristor

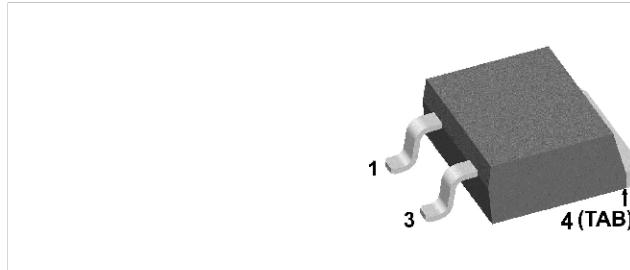
V_{RRM} = 1200 V
 I_{TAV} = 15 A
 V_T = 1.35 V

Three Quadrants operation: QI - QIII
1~ Triac

Part number

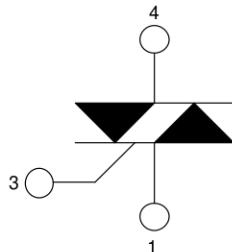
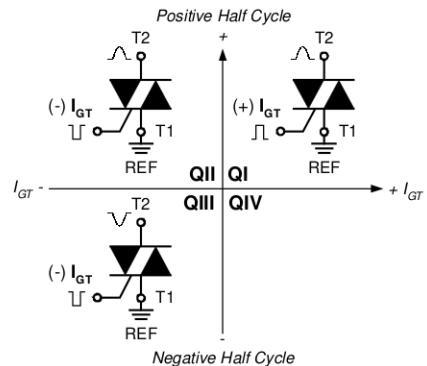
CLA30MT1200NPZ

Marking on Product: *CLA30MT1200NPZ*



Backside: anode/cathode

Three Quadrants Operation



Features / Advantages:

- Triac for line frequency
- Three Quadrants Operation - QI - QIII
- Planar passivated chip
- Long-term stability of blocking currents and voltages

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: TO-263 (D2Pak-HV)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- High creepage distance between terminals

Disclaimer Notice

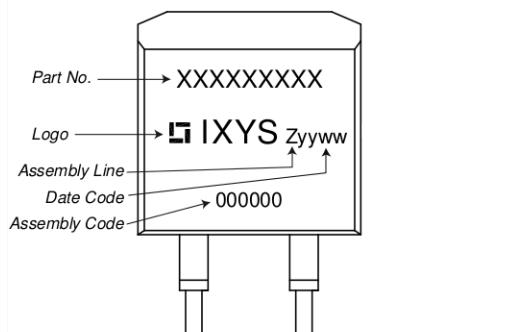
Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics.

Rectifier

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ\text{C}$			1300	V
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ\text{C}$			1200	V
$I_{R/D}$	reverse current, drain current	$V_{R/D} = 1200 \text{ V}$ $V_{R/D} = 1200 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		10 1.5	μA mA
V_T	forward voltage drop	$I_T = 15 \text{ A}$ $I_T = 30 \text{ A}$ $I_T = 15 \text{ A}$ $I_T = 30 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		1.35 1.68 1.35 1.79	V V V V
I_{TAV}	average forward current	$T_C = 120^\circ\text{C}$	$T_{VJ} = 150^\circ\text{C}$		15	A
I_{RMS}	RMS forward current per phase	180° sine			33	A
V_{TO}	threshold voltage	$\left. \begin{array}{l} \text{slope resistance} \\ \end{array} \right\} \text{for power loss calculation only}$	$T_{VJ} = 150^\circ\text{C}$		0.89	V
r_T	slope resistance				30	$\text{m}\Omega$
R_{thJC}	thermal resistance junction to case				0.95	K/W
R_{thCH}	thermal resistance case to heatsink			0.25		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ\text{C}$		130	W
I_{TSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0 \text{ V}$ $T_{VJ} = 150^\circ\text{C}$ $V_R = 0 \text{ V}$		170 185 145 155	A A
I^2t	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0 \text{ V}$ $T_{VJ} = 150^\circ\text{C}$ $V_R = 0 \text{ V}$		145 140 105 100	A^2s A^2s A^2s A^2s
C_J	junction capacitance	$V_R = 400 \text{ V}$ $f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ\text{C}$		9	pF
P_{GM}	max. gate power dissipation	$t_P = 30 \mu\text{s}$ $t_P = 300 \mu\text{s}$	$T_C = 150^\circ\text{C}$		5 1	W W
P_{GAV}	average gate power dissipation				0.2	W
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 150^\circ\text{C}; f = 50 \text{ Hz}$ repetitive, $I_T = 45 \text{ A}$ $t_P = 200 \mu\text{s}; di_G/dt = 0.3 \text{ A}/\mu\text{s};$ $I_G = 0.3 \text{ A}; V = \frac{2}{3} V_{DRM}$ non-repet., $I_T = 15 \text{ A}$			150	$\text{A}/\mu\text{s}$
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty$; method 1 (linear voltage rise)	$T_{VJ} = 150^\circ\text{C}$		500	$\text{V}/\mu\text{s}$
V_{GT}	gate trigger voltage	$V_D = 6 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$		1.3 1.6	V V
I_{GT}	gate trigger current	$V_D = 6 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$		± 40 ± 60	mA mA
V_{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150^\circ\text{C}$		0.2	V
I_{GD}	gate non-trigger current				± 1	mA
I_L	latching current	$t_p = 10 \mu\text{s}$ $I_G = 0.3 \text{ A}; di_G/dt = 0.3 \text{ A}/\mu\text{s}$	$T_{VJ} = 25^\circ\text{C}$		70	mA
I_H	holding current	$V_D = 6 \text{ V}$ $R_{GK} = \infty$	$T_{VJ} = 25^\circ\text{C}$		50	mA
t_{gd}	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$ $I_G = 0.3 \text{ A}; di_G/dt = 0.3 \text{ A}/\mu\text{s}$	$T_{VJ} = 25^\circ\text{C}$		2	μs
t_q	turn-off time	$V_R = 100 \text{ V}; I_T = 15 \text{ A}; V = \frac{2}{3} V_{DRM}$ $T_{VJ} = 125^\circ\text{C}$ $di/dt = 10 \text{ A}/\mu\text{s}$ $dv/dt = 20 \text{ V}/\mu\text{s}$ $t_p = 200 \mu\text{s}$		150		μs

Package TO-263 (D2Pak-HV)

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
I_{RMS}	RMS current	per terminal			35	A
T_{VJ}	virtual junction temperature		-40		150	°C
T_{op}	operation temperature		-40		125	°C
T_{stg}	storage temperature		-40		150	°C
Weight				1.5		g
F_c	mounting force with clip		20		60	N
$d_{Spp/App}$	creepage distance on surface / striking distance through air	terminal to terminal	4.2			mm
$d_{Spb/Abp}$		terminal to backside	4.7			mm

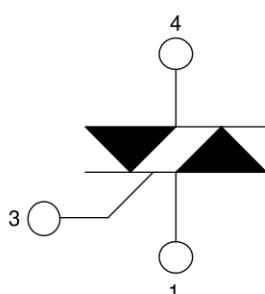
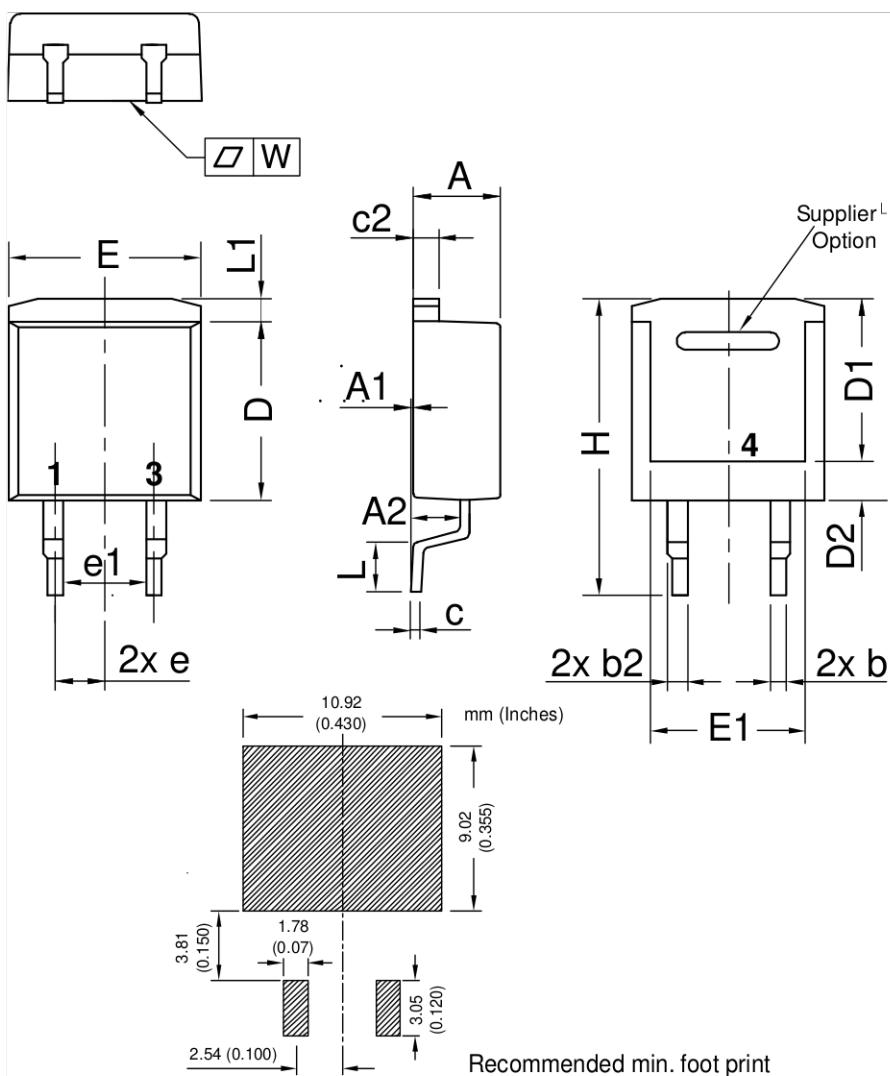
Product Marking

Part description

C = Thyristor (SCR)
 L = High Efficiency Thyristor
 A = (up to 1200V)
 30 = Current Rating [A]
 MT = 1~ Triac
 1200 = Reverse Voltage [V]
 N = Three Quadrants operation: QI - QIII
 PZ = TO-263AB (D2Pak) (2HV)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	CLA30MT1200NPZ-TRL	CLA30MT1200NPZ	Tape & Reel	800	516960
Alternative	CLA30MT1200NPZ-TUB	CLA30MT1200NPZ	Tube	50	525255

Similar Part	Package	Voltage class
CLA30MT1200NPB	TO-220AB (3)	1200

Equivalent Circuits for Simulation
** on die level*
 $T_{VJ} = 150$ °C


Outlines TO-263 (D2Pak-HV)


Thyristor

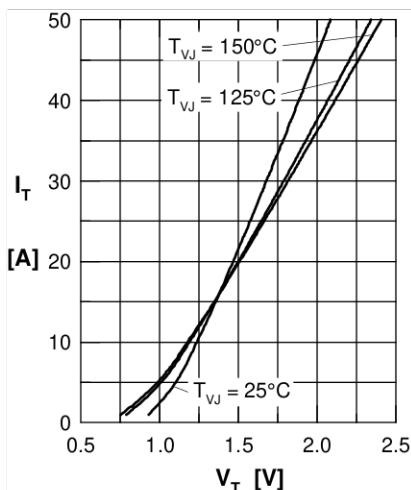


Fig. 1 Forward characteristics

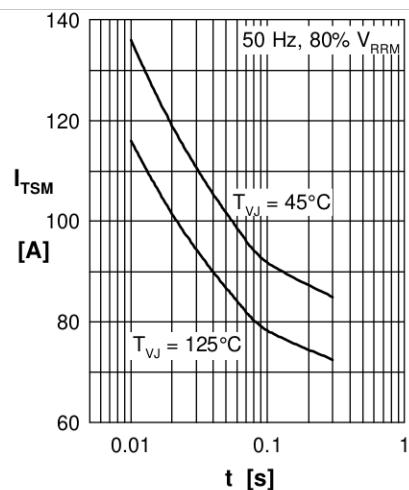


Fig. 2 Surge overload current

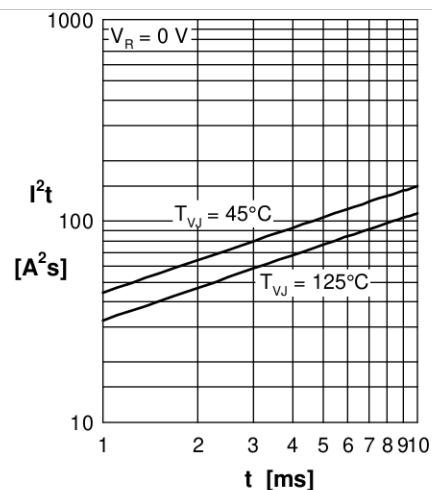


Fig. 3 I^2t versus time (1-10 ms)

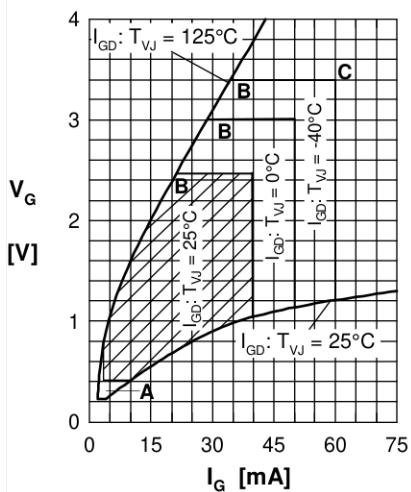


Fig. 4 Gate trigger characteristics

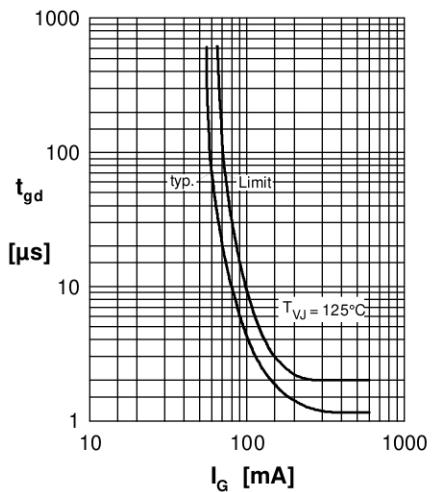


Fig. 5 Gate controlled delay time

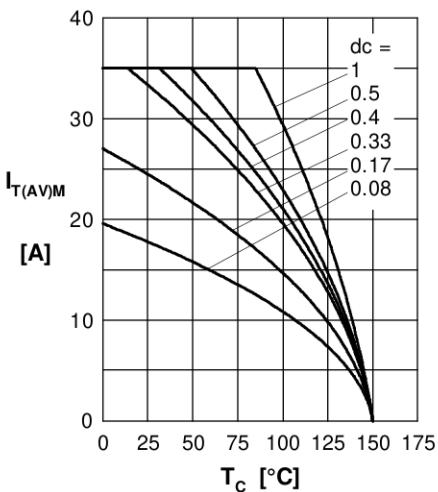


Fig. 6 Max. forward current at case temperature

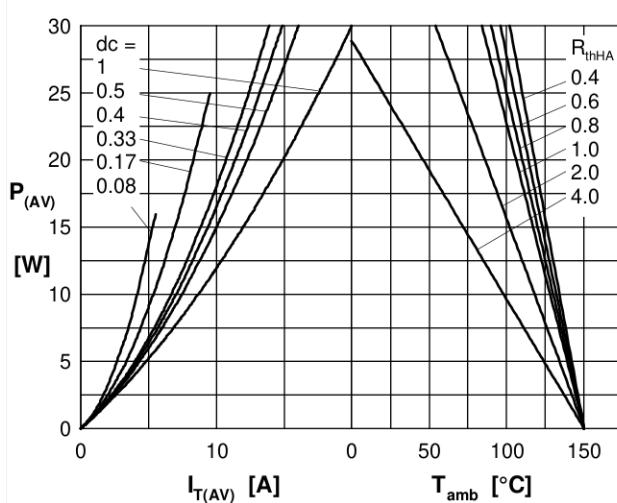


Fig. 7a Power dissipation versus direct output current
Fig. 7b and ambient temperature

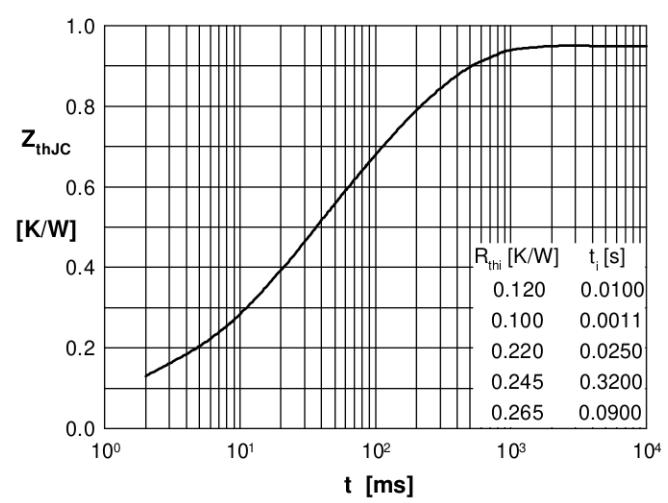


Fig. 8 Transient thermal impedance